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HD74HC04

Hex Inverters



ADE-205-406 (Z) 1st. Edition Sep. 2000

Features

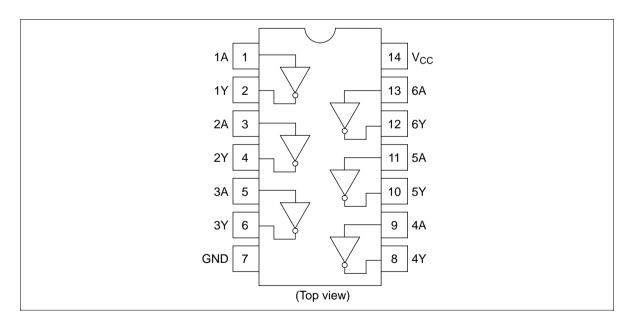
High Speed Operation: t_{pd} = 7.5 ns typ (C_L = 50 pF)
 High Output Current: Fanout of 10 LSTTL Loads

• Wide Operating Voltage: $V_{CC} = 2$ to 6 V

• Low Input Current: 1 μA max

• Low Quiescent Supply Current: I_{CC} (static) = 1 μ A max (Ta = 25°C)

Pin Arrangement



HD74HC04

DC Characteristics

			Ta = 25°C		Ta = −40 to +85°C		_			
Item	Symbol	V _{cc} (V)	Min	Тур	Max	Min	Max	Unit	Test Condition	ns
Input voltage	V _{IH}	2.0	1.5	_	_	1.5	_	V		
		4.5	3.15	i —	_	3.15	_	_		
		6.0	4.2	_	_	4.2	_	=		
	V _{IL}	2.0	_	_	0.5	_	0.5	V		
		4.5	_	_	1.35	_	1.35	=		
		6.0	_	_	1.8	_	1.8	=		
Output voltage	V _{OH}	2.0	1.9	2.0	_	1.9	_	V	$Vin = V_{IH} \text{ or } V_{IL}$	$I_{OH} = -20 \mu A$
		4.5	4.4	4.5	_	4.4	_	=		
		6.0	5.9	6.0	_	5.9	_	=		
		4.5	4.18	s —	_	4.13	_	=		$I_{OH} = -4 \text{ mA}$
		6.0	5.68	3 —	_	5.63	_	=		$I_{OH} = -5.2 \text{ mA}$
	V _{OL}	2.0	_	0.0	0.1	_	0.1	V	$Vin = V_{IH} \text{ or } V_{IL}$	I _{OL} = 20 μA
		4.5	_	0.0	0.1	_	0.1	=		
		6.0	_	0.0	0.1	_	0.1	=		
		4.5	_	_	0.26	_	0.33	_		I _{OL} = 4 mA
		6.0	_	_	0.26	_	0.33	_		I _{OL} = 5.2 mA
Input current	lin	6.0	_	_	±0.1	_	±1.0	μΑ	Vin = V _{CC} or GND	
Quiescent supply current	I _{cc}	6.0	_	_	1.0	_	10	μΑ	Vin = V_{CC} or GND, lout = 0 μ A	

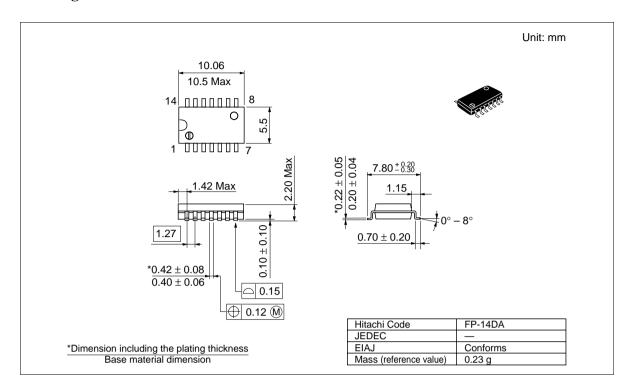
AC Characteristics ($C_L = 50 \text{ pF}$, Input $t_r = t_f = 6 \text{ ns}$)

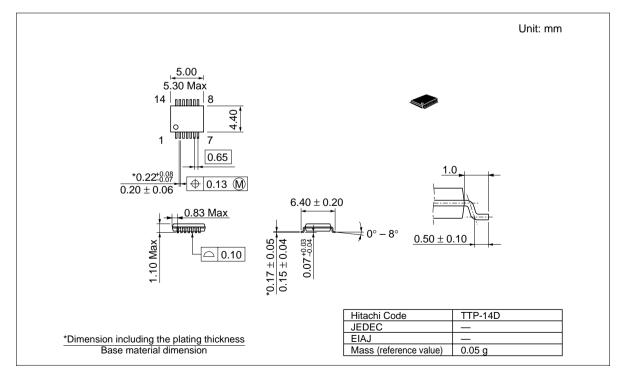
Ta = -40 to Ta = 25°C +85°C

Item	Symbol	V _{cc} (V)	Min	Тур	Max	Min	Max	Unit	Test Conditions
Propagation delay	t _{PLH}	2.0	_	_	90	_	115	ns	
time		4.5	_	7	18	_	23		
		6.0	_	_	15	_	20	_	
	t _{PHL}	2.0	_	_	90	_	115	ns	
		4.5	_	8	18	_	23	_	
		6.0	_	_	15	_	20	=	
Output rise time	t _{TLH}	2.0	_	_	75	_	95	ns	
		4.5	_	5	15	_	19	_	
		6.0	_	_	13	_	16	=	
Output fall time	t _{THL}	2.0	_	_	75	_	95	ns	
		4.5	_	5	15	_	19	=	
		6.0	_	_	13	_	16	=	
Input capacitance	Cin			5	10		10	pF	

HD74HC04

Package Dimensions





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